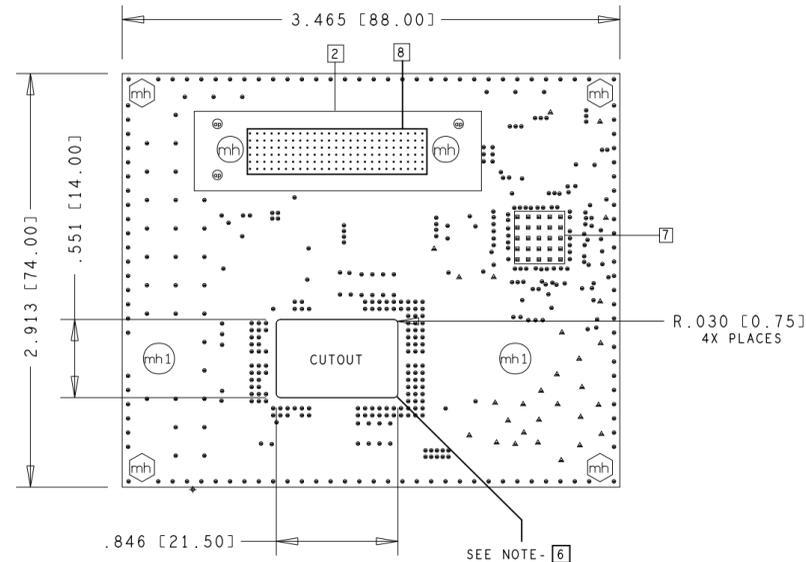


DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	10.0	+3.0/-3.0	PLATED	448
·	10.01	+3.0/-3.0	PLATED	150
▪	12.01	+3.0/-3.0	PLATED	25
▲	24.02	+3.0/-3.0	PLATED	28
⊕	134.65	+3.0/-3.0	PLATED	4
⊖	182.01	+3.0/-3.0	PLATED	2
⊗	66.93	+2.0/-0.0	NON-PLATED	3
⊙	216.54	+2.0/-2.0	NON-PLATED	2

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES[MILLIMETERS] UNLESS OTHERWISE SPECIFIED
- THE PWB SHALL BE FABRICATED TO IPC-6011 AND IPC-6012, CLASS 2, TYPE 3. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
- BOARD MATERIAL -REFER STACKUP. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
- UL RECOGNIZED COMPONENT (ZPMV2) - FLAMMABILITY RATING: 94V-0 DIRECT SUPPORT RATING PER UL796: YES (-DELTA- MARKING OPTIONAL) TEMPERATURE RATING: 105 DEGREES C MINIMUM.
- ELECTRICAL TEST MARKINGS SHOULD BE LEGIBLE PERMANENT AND LOCATED ON THE SECONDARY SIDE OF THE BOARD AND WITHSTAND WAVE SOLDER. LOCATION SHOULD NOT BE UNDER COMPONENTS. UL LOGO AND 94V-0 FLAMMABILITY RATING SHOULD BE ETCHED ON THE SECONDARY SIDE OF THE BOARD.
- IONIC CONTAMINATION LEVEL 10 ug/IN SQ MAXIMUM.
- VERIFICATION OF GOLD AND NICKEL PLATING THICKNESS REQUIRED FOR EACH FABRICATION LOT.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
- OVERALL BOARD THICKNESS TO BE .063 INCHES +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX. WARP & TWIST TO BE .005 INCHES PER INCH.
- MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
- NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
- ALL HOLES IN DRILL CHART ARE FINISHED HOLE SIZES (FHS)
- NO VENDOR LOGO, ART WORKS SHOULD NOT BE CHANGED WITHOUT PRIOR APPROVAL FROM PACTRON
- TEARDROPS SHOULD NOT BE ADDED ON ANY AREA WITHOUT PRIOR APPROVAL FROM PACTRON
- SEE DETAIL A FOR IMPEDANCE REQUIREMENTS AND COPPER WEIGHTS



PROCESS NOTES:

- EXCEPT AS NOTED BELOW, ALL EXPOSED CONDUCTORS ON BOTH SIDES OF THE PWB SHALL BE ELECTROLYTIC PLATED WITH MINIMUM 150 MICRO-INCHES OF NICKEL UNDER 5-15 MICRO-INCHES OF GOLD.
- PLATE INDICATED AREA (BOTH SIDES) WITH ELECTROLYTIC PLATING 100-200 MICRO-INCHES OF NICKEL UNDER 35-50 MICRO-INCHES OF GOLD.
- APPLY LPI SOLDERMASK. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV. COLOR: GREEN.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- NEED TO CUT THE BOARD AS PER MARKED DIMENSION
- MARKED REGION VIAS NEED TO BE SOLDERMASK PLUGGING ON BOTTOM SIDE
- MARKED REGION VIAS NEED TO BE NON CONDUCTIVE VIA FILLING WITH PLATED OVER FLAT AND SMOOTHE ON TOP SIDE
- REMOVE UNUSED PADS IN ALL INNER LAYERS
- DEBURR ALL SHARP EDGES
- CLIP SILKSCREEN ON NO MASK AREA

DETAIL-A	50ohm SINGLE ENDED IMPEDANCE CONTROL +/- 10%	100ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%
TOP (0.5 oz + PLATING)	7.37 MIL	-----
IT-180A DIELECTRIC (4.24 mils)		
02_PWR (2 oz)		
IT-180A DIELECTRIC (7.09 mils)		
03_GND1 (2 oz)		
IT-180A DIELECTRIC (6.42 mils)		
04_SIG1 (1 oz)	5.3 MIL	3.71/6.29 MIL
IT-180A DIELECTRIC (7.09 mils)		
05_GND2 (2 oz)		
IT-180A DIELECTRIC (6.42 mils)		
06_SIG2 (1 oz)	5.3 MIL	3.71/6.29 MIL
IT-180A DIELECTRIC (7.09 mils)		
07_GND3 (2 oz)		
IT-180A DIELECTRIC (4.65 mils)		
BOTTOM (0.5 oz + PLATING)	8.37 MIL	-----
TOTAL THICKNESS: 63 mils +/-10%		

CUSTOMER NAME				PACTRON			
BOARD NAME				DESCRIPTION			
DLPLCR55EVM_DLP093				FAB			
BOARD NO.	REV	DATE					
305-PD-23-0226	1	MAR 2023					